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Part Number:

0737802243

Status:

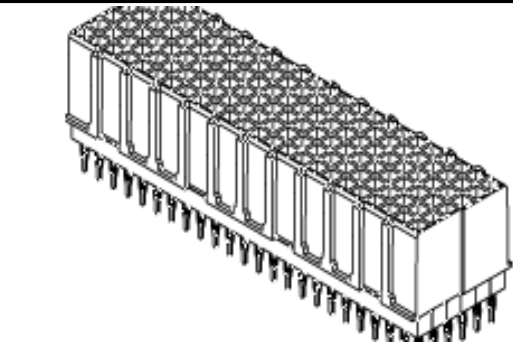
Active

Overview:

HDM® Backplane Connector System

Description:

HDM® Board-to-Board Daughtercard Receptacle, Vertical, Signal Module, 72 Circuits, Mounted Height 13.00mm, Pin Length 3.00mm, Press-Fit



Series image - Reference only

Documents:

3D Model

Drawing (PDF)

Product Specification PS-73780-999 (PDF)

Test Summary TS-73670-990 (PDF)

RoHS Certificate of Compliance (PDF)

Agency Certification	
UL	E29179
General	
Product Family	Backplane Connectors
Series	73780
Application	Daughtercard, Mezzanine
Comments	Press-Fit Tail
Component Type	PCB Receptacle
Overview	HDM® Backplane Connector System
Product Name	HDM®
UPC	800756059938
Physical	
Circuits (Loaded)	72
Circuits (maximum)	72
Color - Resin	Black
Durability (mating cycles max)	250
First Mate / Last Break	No
Flammability	94V-0
Guide to Mating Part	No
Keying to Mating Part	None
Material - Metal	Copper-Nickel-Tin
Material - Plating Mating	Gold
Material - Plating Termination	Tin-Lead
Material - Resin	High Temperature Thermoplastic
Net Weight	9.498/g
Number of Columns	12
Number of Pairs	Open Pin Field
Number of Rows	6
Orientation	Vertical
PC Tail Length	3.00mm
PCB Locator	No
PCB Retention	None
PCB Thickness - Recommended	1.60mm
Packaging Type	Tube
Pitch - Mating Interface	2.00mm
Pitch - Termination Interface	2.00mm
Plating min - Mating	0.762µm
Plating min - Termination	0.889µm
Polarized to PCB	No
Stackable	Yes
Surface Mount Compatible (SMC)	Yes
Temperature Range - Operating	-55°C to +105°C
Termination Interface: Style	Through Hole - Compliant Pin

EU ELV

Not Relevant

EU RoHS

China RoHS

Compliant

REACH SVHC

Contains SVHC(2014 December 17): No

Halogen-Free

Status

Low-Halogen

Need more information on product environmental compliance?

Email productcompliance@molex.com

Please visit the [Contact Us](#) section for any non-product compliance questions.

China ROHS

Green Image

ELV

Not Relevant

Search Parts in this Series

73780 Series

Mates With

HDM® Board-to-Board Backplane Header [73642](#) , [73643](#) , [73644](#) , [73942](#) , [73943](#) , [73944](#) , [74349](#) , [74428](#). HDM® Board-to-Board Stacking Header [73769](#) , [73770](#) , [73782](#) , [73783](#) , [73771](#)

Electrical

Current - Maximum per Contact	15.0A, 1.0A
Data Rate	1.0 Gbps
Real Signals (per 25mm)	75
Shielded	No
Voltage - Maximum	250V AC

Solder Process Data

Lead-freeProcess Capability	N/A
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Material Info

Reference - Drawing Numbers

Product Specification	PS-73780-999
Sales Drawing	SD-73780-001
Test Summary	TS-73670-990

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This document was generated on 06/24/2015

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